AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (canceled).

Claim 2 (currently amended): A surface acoustic wave device according to claim ~~1~~5, wherein the surface acoustic wave device is a longitudinally coupled resonator type surface acoustic wave filter in which at least three IDTs are disposed along the surface acoustic wave propagation direction.

Claim 3 (original): A surface acoustic wave device according to claim 2, wherein the surface acoustic wave device includes a plurality of the longitudinally coupled resonator type surface acoustic wave filters.

Claim 4 (currently amended): A surface acoustic wave device according to claim ~~1~~5, wherein there is no electrically neutral point between the first and second balanced signal terminals.

Claim 5 (currently amended): ~~A surface acoustic wave device according to claim 1, further comprising~~ A surface acoustic wave device comprising:

a piezoelectric substrate;

at least one IDT disposed on the piezoelectric substrate;

an input end and an output end connected to the IDT, at least one of the input end and the output end including a pair of balanced signal terminals;

at least one of a delay line and a reactance component connected to one of the pair of balanced signal terminals; and

a package and a microstrip line provided on one of the package and the piezoelectric substrate, wherein the microstrip line constitutes at least one of the delay line and the reactance component.

Claim 6 (original): A surface acoustic wave device according to claim 5, further comprising a plurality of IDTs disposed on the piezoelectric substrate and housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

Claim 7 (currently amended): A surface acoustic wave device according to claim ~~1~~5, ~~further comprising a~~ wherein the package ~~having~~ has electrodes disposed thereon~~,~~; ~~wherein~~

the electrodes of the package are electrically connected to at least one of the input and output ends having the first and second balanced signal terminals via a bonding wire~~,~~; and ~~wherein~~

the bonding wire constitutes at least one of the delay line and the reactance component.

Claim 8 (currently amended): A communication device containing a surface acoustic wave device according to claim ~~1~~5.

Claim 9 (canceled).

Claim 10 (currently amended): A surface acoustic wave device according to claim ~~9~~13, wherein the surface acoustic wave device is a longitudinally coupled

resonator type surface acoustic wave filter in which at least three IDTs are disposed along the surface acoustic wave propagation direction.

Claim 11 (original): A surface acoustic wave device according to claim 10, wherein the surface acoustic wave device includes a plurality of the longitudinally coupled resonator type surface acoustic wave filters.

Claim 12 (currently amended): A surface acoustic wave device according to claim ~~9~~13, wherein there is no electrically neutral point between the first and second balanced signal terminals.

Claim 13 (currently amended): ~~A surface acoustic wave device according to claim 9, further comprising~~ A surface acoustic wave device comprising:

a piezoelectric substrate;

at least one IDT disposed on the piezoelectric substrate;

an input end and an output end connected to the IDT, at least one of the input end and the output end including a pair of balanced signal terminals;

at least one of a plurality of delay lines and a plurality of reactance components connected to the pair of balanced signal terminals, respectively, and being different from each other; and

a package and a microstrip line provided on one of the package and the piezoelectric substrate, wherein the microstrip line constitutes at least one of the delay line and the reactance component.

Claim 14 (original): A surface acoustic wave device according to claim 13, further comprising a plurality of IDTs disposed on the piezoelectric substrate and housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

Claim 15 (currently amended): A surface acoustic wave device according to claim 9, ~~further comprising a~~ wherein the package ~~having~~has electrodes disposed thereon~~,~~; ~~wherein~~

the electrodes of the package are electrically connected to at least one of the input and output ends having the first and second balanced signal terminals via a bonding wire~~,~~; and

wherein the bonding wire constitutes at least one of the delay line and the reactance component.

Claim 16 (currently amended): A communication device containing a surface acoustic wave device according to claim ~~8~~13.

Claim 17 (previously presented): A surface acoustic wave device comprising:

a piezoelectric substrate;

a plurality of IDTs disposed on the piezoelectric substrate forming a plurality of longitudinally coupled resonator type surface acoustic wave filters;

at least one of an input end of the surface acoustic wave device and an output end of the surface acoustic wave device includes a pair of balanced signal terminals; and

a capacitance component connected between the pair of balanced signal terminals.

Claim 18 (previously presented): A surface acoustic wave device according to claim 17, wherein at least one of the plurality of longitudinally coupled resonator type surface acoustic wave filters includes at least three IDTs disposed along the surface acoustic wave propagation direction.

Claim 19 (canceled).

Claim 20 (original): A surface acoustic wave device according to claim 17, wherein there is no electrically neutral point between the pair of balanced signal terminals.

Claim 21 (original): A surface acoustic wave device according to claim 17, further comprising a package and a microstrip line provided on one of the package and the piezoelectric substrate, wherein the microstrip line constitutes the capacitance component.

Claim 22 (original): A surface acoustic wave device according to claim 21, further comprising a plurality of IDTs disposed on the piezoelectric substrate and housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

Claim 23 (previously presented): A surface acoustic wave device according to claim 17, further comprising a package having electrodes disposed thereon, wherein the electrodes of the package are electrically connected to at least one of the input and output ends having the pair of balanced signal terminals via a bonding wire, and wherein the bonding wire is connected to the capacitance component.

Claim 24 (original): A communication device containing a surface acoustic wave device according to claim 17.